

L Number	Hits	Search Text	DB	Time stamp
1	6010	solder near3 (melting adj point or melting near3 temperature)	USPAT; US-PGPUB	2004/08/02 11:17
2	1024	(solder near3 (melting adj point or melting near3 temperature)) and optical	USPAT; US-PGPUB	2004/08/02 11:16
3	844	((solder near3 (melting adj point or melting near3 temperature)) and optical) and (bond bonding bonded)	USPAT; US-PGPUB	2004/08/02 11:16
4	50221	(lower higher greater less) near5 (melting adj point or melting near3 temperature)	USPAT; US-PGPUB	2004/08/02 11:18
5	386	((solder near3 (melting adj point or melting near3 temperature)) and optical) and (bond bonding bonded)) and ((lower higher greater less) near5 (melting adj point or melting near3 temperature))	USPAT; US-PGPUB	2004/08/02 11:23
6	213	((solder near3 (melting adj point or melting near3 temperature)) and optical) and (bond bonding bonded)) and ((lower higher greater less) near5 (melting adj point or melting near3 temperature))) and @pd<20020620	USPAT; US-PGPUB	2004/08/02 11:24
8	31	(US-6046909-\$ or US-6005777-\$ or US-5956415-\$ or US-6492699-\$ or US-6052287-\$ or US-6495895-\$ or US-6515269-\$ or US-6512219-\$ or US-6627864-\$ or US-6674159-\$ or US-5087964-\$ or US-5122861-\$ or US-5196919-\$ or US-5612549-\$ or US-6384473-\$ or US-6072232-\$ or US-6350113-\$ or US-6428650-\$ or US-5297333-\$ or US-6603183-\$ or US-5898215-\$ or US-5449908-\$ or US-5612256-\$ or US-5936848-\$ or US-5798557-\$ or US-6252229-\$).did. or (US-6686653-\$ or US-4178529-\$ or US-6122009-\$).did. or (US-20010028557-\$ or US-20020023765-\$ or US-20020027265-\$ or US-20030222333-\$ or US-20030146384-\$).did. or (EP-1289281-\$).did. or (JP-11354769-\$).did. or (WO-200165836-\$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/02 12:45
9	21	((US-6603183-\$) or US-6384473-\$ or US-5087964-\$ or US-5798557-\$ or US-5196919-\$ or US-5122861-\$ or US-5612549-\$ or US-5898215-\$ or US-5689106-\$ or US-6072232-\$ or US-6005777-\$ or US-5936848-\$ or US-6046909-\$ or US-6052287-\$ or US-6674159-\$ or US-6627864-\$ or US-6603183-\$ or US-6515269-\$ or US-6512219-\$ or US-6495895-\$ or US-6492699-\$).did. or (US-20010028557-\$).did. or (JP-11354769-\$).did.	USPAT; US-PGPUB; JPO	2004/08/02 12:45
10	20	(US-5122861-\$ or US-4590539-\$ or US-4841100-\$ or US-6384473-\$ or US-5640207-\$ or US-4622580-\$ or US-5087964-\$ or US-5903706-\$ or US-6541837-\$ or US-6072232-\$ or US-5689106-\$ or US-5612549-\$ or US-5319521-\$ or US-5314742-\$ or US-5196919-\$ or US-5223741-\$ or US-5296724-\$ or US-5895233-\$ or US-3934074-\$).did. or (US-20030128291-\$ or US-20030146384-\$).did. or (EP-1289281-\$).did. or (JP-11354769-\$).did. or (WO-200165836-\$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/02 12:45
11	21	(US-5956415-\$ or US-5612256-\$ or US-5449908-\$ or US-5297333-\$ or US-6072232-\$ or US-6046909-\$ or US-6674159-\$ or US-6627864-\$ or US-6515269-\$ or US-6512219-\$ or US-6492699-\$ or US-6052287-\$ or US-6005777-\$ or US-5936848-\$ or US-5898215-\$ or US-6495895-\$ or US-5612549-\$ or US-5196919-\$ or US-5122861-\$ or US-5087964-\$).did. or (US-20010028557-\$).did. or (EP-1289281-\$).did. or (JP-11354769-\$).did. or (WO-200165836-\$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/02 12:45
12	276	((257/432,433,434,436,680,703,704,710,723) or (250/338.1,338.4)).CCLS. and @pd>20040310	USPAT; US-PGPUB	2004/08/02 12:46
13	20	(solid-state-imaging solid-state adj imaging solid-state adj imager) and resin and @pd>20040310	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:47
14	5	imager WITH circuit adj board and @pd>20040310	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:47
15	41	flip-chip and (ccd optical adj sensor) and @pd>20040310	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:47
16	13	(flip-chip and (ccd optical adj sensor) and @pd>20040310) and infrared	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:47

17	11	5,895,233 and @pd>20040310	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:48
18	3	(5,895,233 and @pd>20040310) and infrared	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:48
19	3	(5,895,233 and @pd>20040310) and infrared and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 12:48